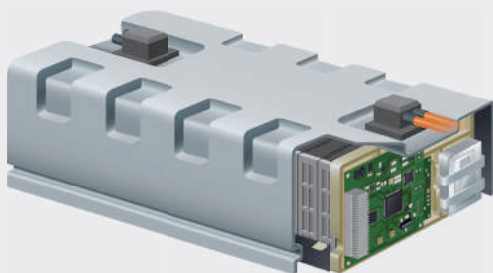


# Non-Conductive Via Filling Paste

Over 20-year experience for automotive and high-end industries

## Applications

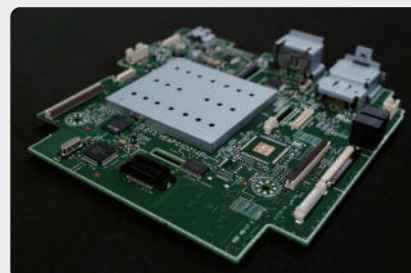
Industrial/automotive industries  
(High Tg requirement)



e.g. : Vehicles



Home electronics  
(High density wiring)

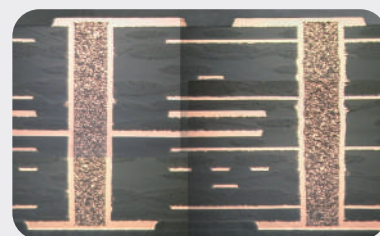


e.g. : Gaming devices



## Features

- Excellent adhesion to various material surfaces including copper foil
- Solvent-free enabling void/crack-free
- Contribution to high-density routing and/or multi-layer build-up



## Product line-up & properties

Product			AE1125HD	AE1125DS
Filler	Conductive particles		Copper	
	Average particle size	μm	5 - 6	
Binder	Resin		Epoxy	
Viscosity	BH type	dPa·s	1,200 - 2,000	800 - 1,600
Density		g/cm <sup>3</sup>	3.7 - 3.9	
Curing conditions	Pre-curing		80°C × 30min.	
	Post-curing		160°C × 60min.	
Volume resistivity(Representative value)		Ω·cm	1.0E+09 - 1.0E+12	
Thermal conductivity (Laser flash method)		W/m·k	1.4	1.1
Glass-transition temperature/Tg		°C	163	210
Shelf-life	-15 ~ -25°C	month(s)	4	8

